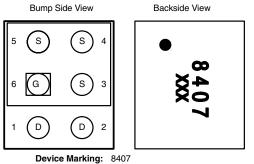


**Vishay Siliconix** 

# P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$V_{DS}$ (V) $R_{DS(on)}$ (Ω) $I_D$ (Λ)			
	0.027 at V <sub>GS</sub> = - 4.5 V	- 8.2		
- 20	0.032 at V <sub>GS</sub> = - 2.5 V	- 7.5		
	0.045 at V <sub>GS</sub> = - 1.8 V	- 6.6		





xxx = Date/Lot Traceability Code

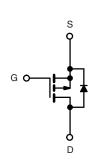
Ordering Information: Si8407DB-T2-E1 (Lead (Pb)-free and Halogen-free)

#### **FEATURES**

- Halogen-free according to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- MICRO FOOT<sup>®</sup> Chipscale Packaging Reduces Ultra-Low Footprint Area Profile (0.62 mm) and On-Resistance
- Compliant to RoHS Directive 2002/95/EC

#### **APPLICATIONS**

- Portable Devices
- PA Switch
- Battery Switch
- Load Switch



P-Channel MOSFET

Parameter		Symbol	5 s	Steady State	Unit	
Drain-Source Voltage		V <sub>DS</sub>	- 20		V	
Gate-Source Voltage		V <sub>GS</sub>	± 8			
Continuous Drain Current $(T_J = 150 \ ^{\circ}C)^a$	T <sub>A</sub> = 25 °C	– I <sub>D</sub>	- 8.2	- 5.8		
	T <sub>A</sub> = 70 °C		- 6.5	- 4.6		
Pulsed Drain Current		I <sub>DM</sub>	- 15		A	
Continuous Source Current (Diode Conduction) <sup>a</sup>		۱ <sub>S</sub>	- 2.6	- 1.34		
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.9	1.47	W	
	T <sub>A</sub> = 70 °C		1.86	0.94		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		О°	
Package Reflow Conditions <sup>b</sup>	IR/Convection		260		-0	
THERMAL RESISTANCE RATING	GS					
Parameter		Symbol	Typical	Maximum	Unit	
Maximum lunction to Ambienta	t ≤ 5 s	R <sub>thJA</sub>	33	43	°C/W	
Maximum Junction-to-Ambient <sup>a</sup>	Steady State	• •tnJA	72	85		
Maximum Junction-to-Foot (drain)	Steady State	R <sub>thJF</sub>	15	19		

a. Surface mounted on 1" x 1" FR4 board.

b. Refer to IPC/JEDEC (J-STD-020), no manual or hand soldering.

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COMPLIANT HALOGEN FREE

# Vishay Siliconix



SPECIFICATIONS (T <sub>J</sub> = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -350 \ \mu A$			- 0.9	V	
Gate-Body Leakage	I <sub>GSS</sub>				± 100	nA	
Zava Cata Valtaga Dvain Current		$V_{DS} = -20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1	μΑ	
Zero Gate Voltage Drain Current	IDSS	$V_{DS}$ = - 20 V, $V_{GS}$ = 0 V, $T_{J}$ = 70 °C	0 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 70 °C		- 5		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \leq$ - 5 V, $V_{GS}$ = - 4.5 V	- 5			Α	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 1 A		0.022	0.027	Ω	
		$V_{GS} = -2.5 \text{ V}, \text{ I}_{D} = -1 \text{ A}$		0.026	0.032		
		V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 1 A		0.033	0.045		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = -10 \text{ V}, \text{ I}_{D} = -1 \text{ A}$		10		S	
Diode Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>S</sub> = - 1 A, V <sub>GS</sub> = 0		- 0.6	- 1.1	V	
Dynamic <sup>b</sup>							
Total Gate Charge	Qg			32	50		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ = - 10 V, $V_{GS}$ = - 4.5 V, $I_D$ = - 1 A		3.6		nC	
Gate-Drain Charge	Q <sub>gd</sub>			8.5			
Turn-On Delay Time	t <sub>d(on)</sub>			30	45		
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 10 V, $R_L$ = 10 $\Omega$		45	70	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$\rm I_D \cong$ - 1 A, $\rm V_{GEN}$ = - 4.5 V, $\rm R_g$ = 6 $\Omega$		550	825		
Fall Time	t <sub>f</sub>			220	330		
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = - 1 A, dl/dt = 100 A/μs		265	500		

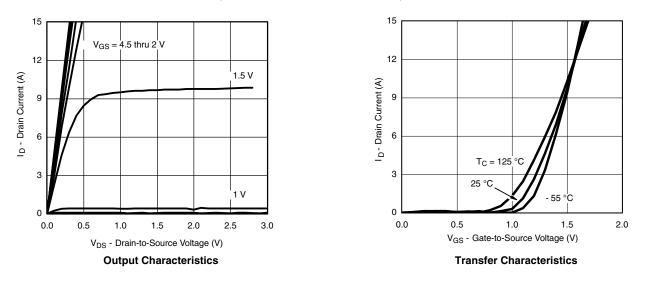
Notes:

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



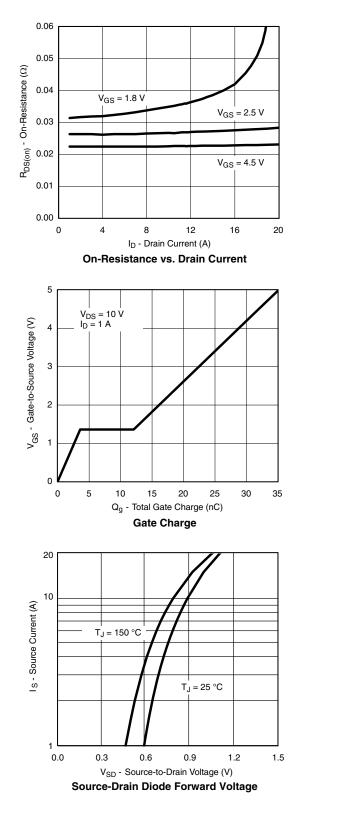
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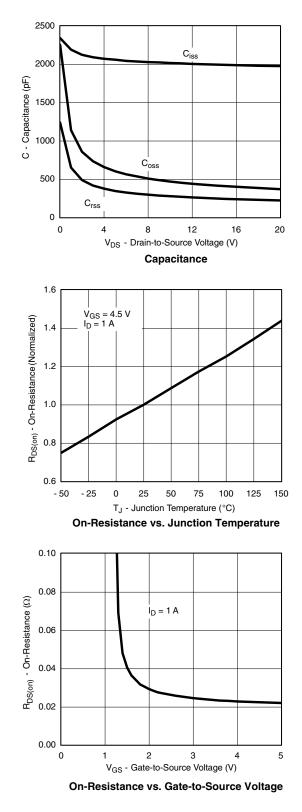
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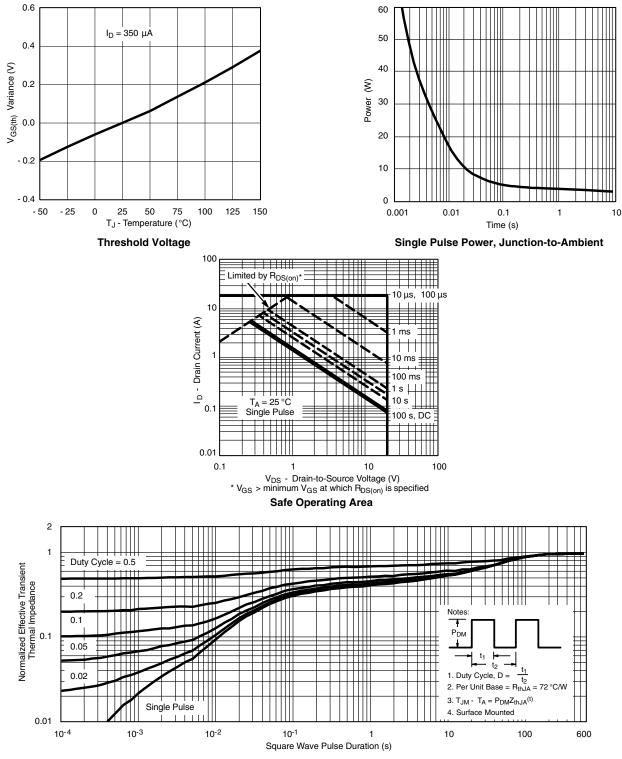




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#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

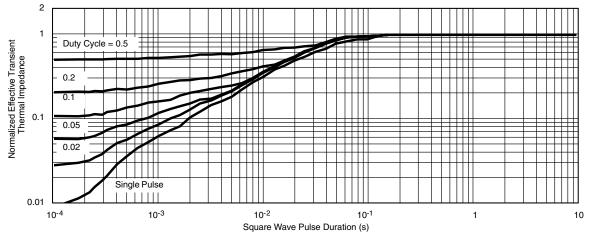
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## Si8407DB Vishay Siliconix

#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



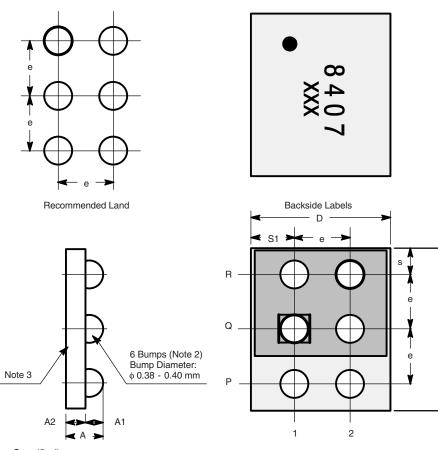
Normalized Thermal Transient Impedance, Junction-to-Foot

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#### PACKAGE OUTLINE

#### MICRO FOOT: 6-BUMP (2.4 mm x 2 mm, 0.8 mm PITCH)



Notes (Unless Otherwise Specified):

1. All dimensions are in millimeters.

2. Bumps are 95.5/3.8/0.7 Sn/Ag/Cu with diameter  $\phi$  0.38 mm - 0.40 mm.

3. Backside surface is coated with a Ti/NI/Ag layer.

4. Non-solder mask defined copper landing pad.

5. The flat side of wafers is oriented at the bottom.

6. • is location of Pin 1P.

Dim.	Millim	eters <sup>a</sup>	Inches		
	Min.	Max.	Min.	Max.	
Α	0.600	0.650	0.0236	0.0256	
A <sub>1</sub>	0.260	0.290	0.0102	0.0114	
A <sub>2</sub>	0.340	0.360	0.0134	0.0142	
b	0.370	0.410	0.0146	0.0161	
D	1.920	2.000	0.0756	0.0787	
E	2.320	2.400	0.0913	0.0945	
е	0.750	0.850	0.0295	0.0335	
S	0.370	0.400	0.0150	0.0157	
S1	0.580	0.600	0.0228	0.0236	

PAD DISTRIBUTION TABLE						
	Р	Q	R			
1	Drain	Gate	Source			
2	Drain	Source	Source			

Notes:

a. Use millimeters as the primary measurement.

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